

Early consideration and allowance of the application are earnestly solicited.

Respectfully submitted,



Peter F. Corless (Reg. 33,860)
EDWARDS & ANGELL, LLP
Dike, Bronstein, Roberts & Cushman IP Group
P.O. Box 9169
Boston, MA 02209
(617) 523-3400

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MARKED VERSION TO SHOW CHANGES

4. (amended) The photoresist of claim 1 [any one of claims 1 through 3] wherein the carbon alicyclic group is a polymerized norbornene group.

5. (amended) The photoresist of claim 1 [any one of claims 1 through 4] wherein the heteroalicyclic group has a non-hydrogen ring substituent.

8. (amended) The photoresist of claim 1 [claim 7] wherein the polymer comprises a polymerized acrylate that comprises a photoacid-labile moiety.

13. (amended) The photoresist of claim 1 [any one of claims 1 through 11] wherein the heteroalicyclic group fused to the polymer backbone is not an anhydride or lactone.

23. (amended) The photoresist of claim 1 [any one of claims 1 through 22] wherein the polymer is a tetrapolymer or a pentopolymer.

24. (amended) The photoresist of claim 1 [any one of claims 1 through 23] wherein the polymer is completely free of aromatic groups.

35. (amended) A method of forming a positive photoresist relief image, comprising:

(a) applying a coating layer of a photoresist of claim 1 [any one of claims 1 through 24] on a substrate; and

(b) exposing and developing the photoresist layer to yield a relief image.

41. (amended) An article of manufacture comprising a microelectronic wafer substrate or flat panel display substrate having coated thereon a layer of the photoresist composition of claim 1 [any one of claims 1 through 24].